

SMD Super Bright LED

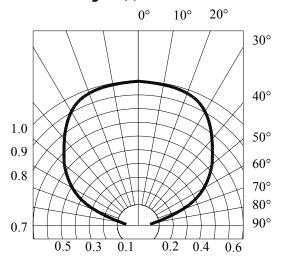
Right Angle Surface Mount LED

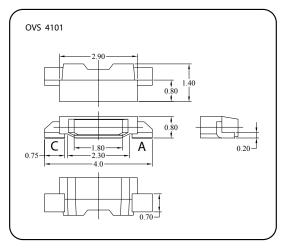
Features:

- Side Emitting LED
- Wide Viewing Angle
- Low Profile Package

Maximum Ratings at Ta=25°C

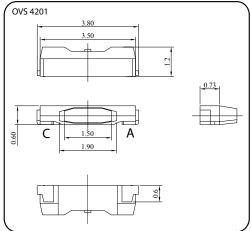
Radiation Diagram(s)





Electrical & Optical Characteristics at Ta=25 °C

Ant Part No.	LED Chip Material	Lens Colour		inates for omaticity A Y Axis	Lumino Intensit at 20m min.	ty (mcd)	Forw Volta at 20 typ.	ge (V)	Viewing Angle 2 θ- ^{1/2} (deg)
OVS-2101	InGaN/ Sapphire	Water Clear	0.31	0.30	900	1300	3.2	4.0	120
OVS-4101	InGaN/ Sapphire	Water Clear	0.31	0.30	900	1300	3.2	4.0	120
OVS-4201	InGaN/ Sapphire	Water Clear	0.31	0.30	700	1100	3.2	4.0	120



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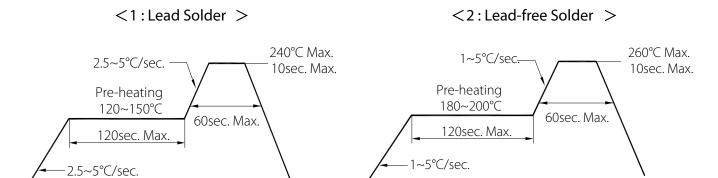


Soldering

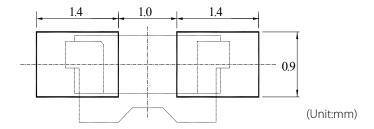
	Reflow Soldering				
	Lead Solder	Lead - free Solder			
Pre-heat	120~150°C	180~200°C			
Pre-heat time	120sec. Max.	120sec. Max.			
Peak temperature	240°C Max.	260°C Max.			
Soldering time	10sec. Max.	10sec. Max.			
Condition	refer to	refer to			
	Temperature-	Temperature-			
	profile 1	profile 2			

^{*}After reflow soldering, rapid cooling should be avoided.

Temperature-profile



Recommended soldering pad design for OVS-2101



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